

**Reliability Data Summary:****Roznov Wafer Fab**

QV DEVICE NAME: One lot LM393, two lots LM358

PACKAGE: Soic 8/14

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/240
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		

Silan Wafer Fab

QV DEVICE NAME: One lot LM393, two lots LM358

PACKAGE: Soic 8/14

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/240
ELFR	JESD22-A108	Ta=125C, 100% max rated Vcc	48 hrs	0/2400
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/240
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		

Electrical Characteristic Summary:

Electrical characterization has been completed with no changes to the AC/DC specifications. ON Semiconductor recommends samples be obtained for application specific review and validation.

As a result of the design modification, the ESD capability will be revised as follows:

Device	from	HBM (V)	MM (V)	to	HBM (V)	MM (V)
LM358DR2G	from	2000	200	to	250	100
LM324DR2G	from	2000	200	to	200	100
LM393DR2G	from	1500	150	to	250	100
LM339DR2G	from	1500	200	to	250	100
LM2901DR2G	from	1500	200	to	250	100
LM2902DR2G	from	2000	200	to	200	100
LM2903DR2G	from	1500	150	to	250	100
LM2904DR2G	from	2000	200	to	250	100

**List of affected Standard Parts:**

Part Number	Qualification Vehicle
LM358DR2G	LM393DR2G + LM324DR2G
LM324DR2G	LM393DR2G + LM324DR2G
LM393DR2G	LM393DR2G + LM324DR2G
LM339DR2G	LM393DR2G + LM324DR2G
LM2901DR2G	LM393DR2G + LM324DR2G
LM2902DR2G	LM393DR2G + LM324DR2G
LM2903DR2G	LM393DR2G + LM324DR2G
LM2904DR2G	LM393DR2G + LM324DR2G